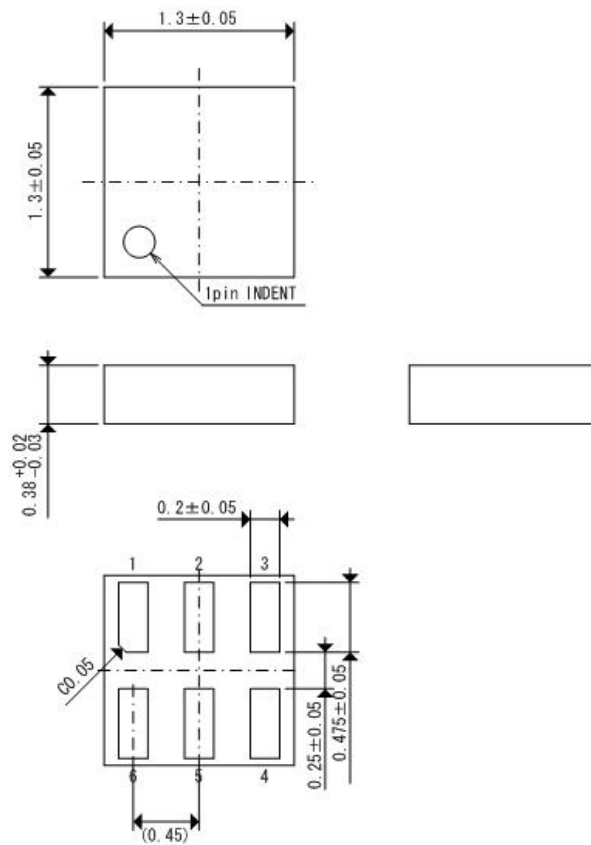


Packaging Information / Reference Pattern Layout Dimensions

●USPN-6

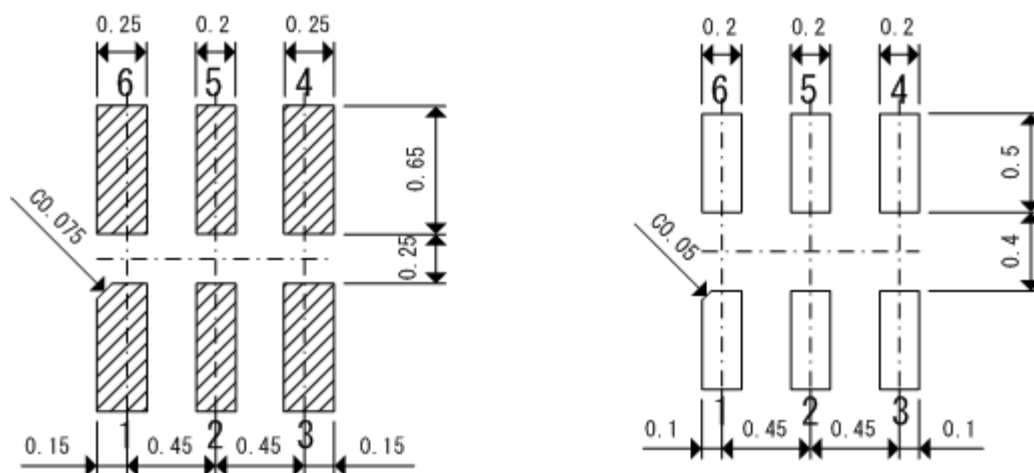
Unit: mm

■Packaging Information



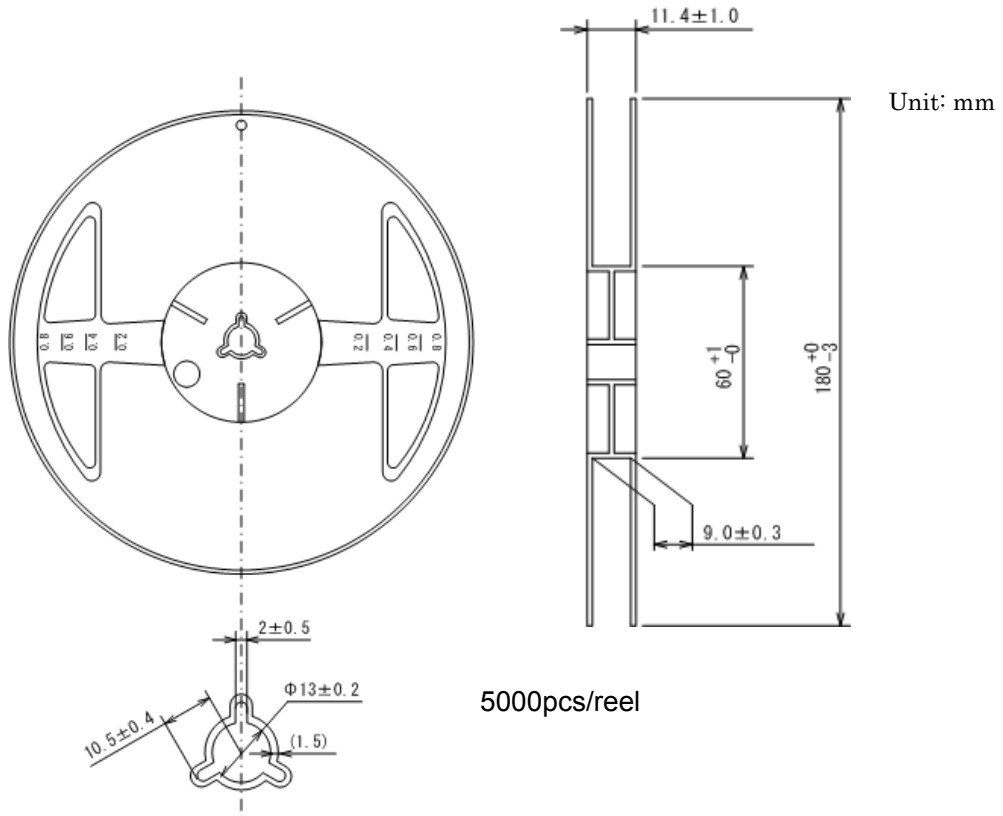
■Reference Pattern Layout Dimension

Note : reference metal mask design



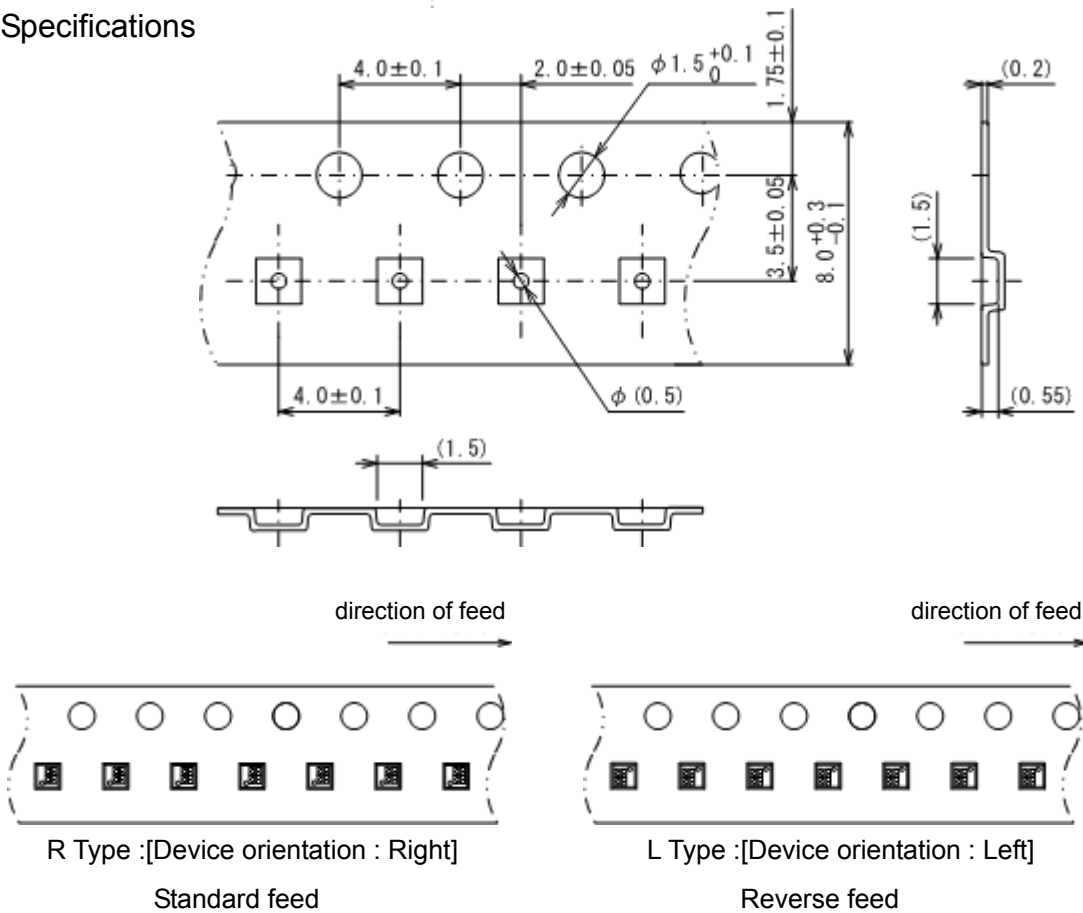
Taping Specifications

●USPN-6 Reel



5000pcs/reel

●Taping Specifications



●USPN-6 Power Dissipation

Power dissipation data for the USPN-6 is shown in this page.

The value of power dissipation varies with the mount board conditions.

Please use this data as one of reference data taken in the described condition.

1. Measurement Condition (Reference data)

Condition : Mount on a board

Ambient : Natural convection

Soldering : Lead (Pb) free

Board : Dimensions 40mm x 40 mm (1600mm²)

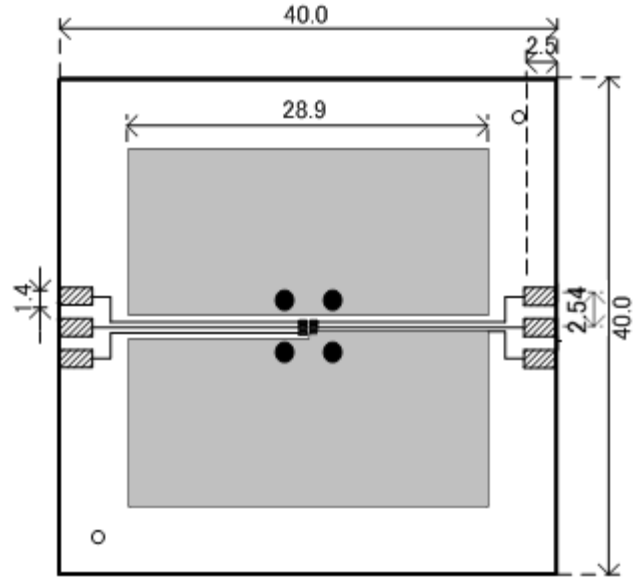
Copper (Cu) traces occupy 50% of the front and 50% of the back.

VSS pin is tied to the copper traces

Material : Glass Epoxy (FR-4)

Thickness : 1.6mm

Through-hole : 4 x 0.8 Diameter

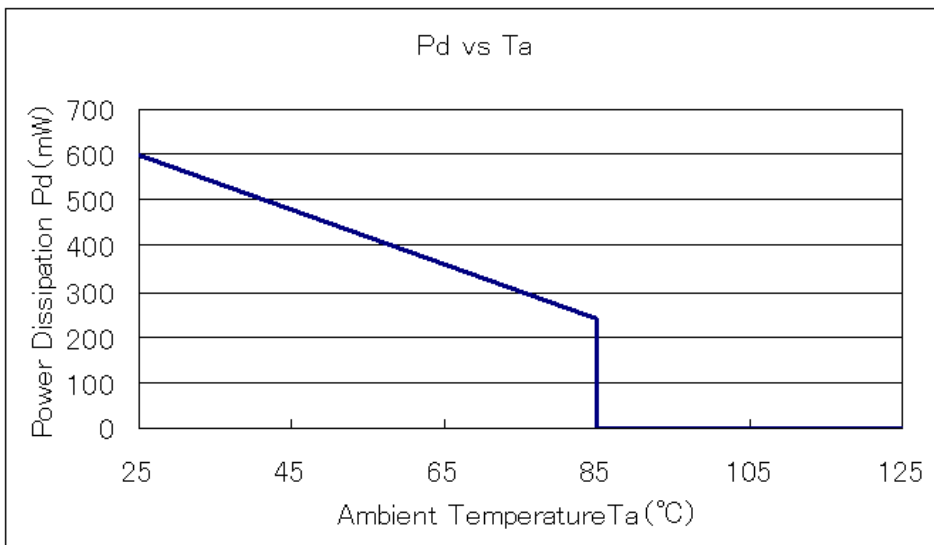


Evaluation Board (Unit: mm)

2. Power Dissipation vs. Ambient temperature

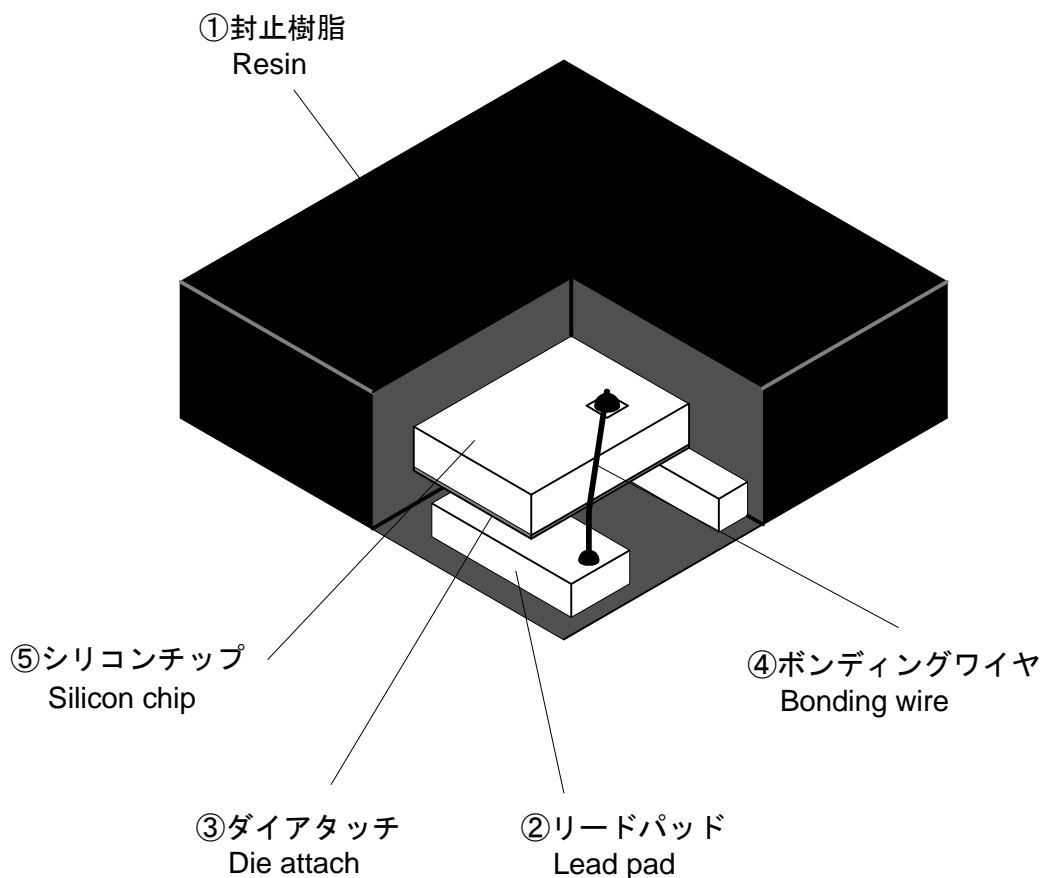
Board Mount (T_{jmax}=125°C)

Ambient Temperature (°C)	Power Dissipation Pd (mW)	Thermal Resistance (°C/W)
25	600	166.67
85	240	



USPN-6 構造図
USPN-6 Perspective

RoHS対応品
 RoHS Compliance



項目 Item	材料 Material	備考 Note
① 封止樹脂 Resin	エポキシ樹脂 Epoxy resin	難燃グレード/Flammability rating UL94V-0
② リードパッド Lead pad	ニッケル Nickel	
	端子処理 Outer pad plating	Auメッキ Gold plating
③ ダイアタッチ Die attach	ダイアタッチフィルム Die attach film	
④ ボンディングワイヤ Bonding wire	Au	
⑤ シリコンチップ Silicon chip	Si	

捺印表示 Marking	レーザー Laser marking
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